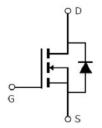


Main Product Characteristics:

V _{DSS}	60V	
R _{DS} (on)	70m	
I _D	2.7A	







SOT-23

Marking and Pin
Assignments

Schematic Diagram

Features and Benefits:

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150 operating temperature



Description:

It utilizes the latest trench processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications

Absolute max Rating:

Symbol	Parameter	Max.	Units		
I _D @ TC = 25°C	Continuous Drain Current, V _{GS} @ 10V	2.7			
I _{DM}	Pulsed Drain Current	10.8	O.8		
P _D @TC = 25°C	Power Dissipation	1.25	W		
	Linear Derating Factor	0.01	W/°C		
V _{DS}	Drain-Source Voltage	60	V		
V _{GS}	Gate-to-Source Voltage ± 20		V		
T _J T _{STG}	Operating Junction and Storage Temperature Range -55 to + 150		°C		





Thermal Resistance

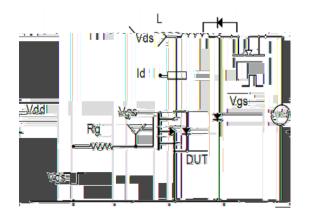
Symbol	Characterizes	Тур.	Max.	Units
	Junction-			

R A

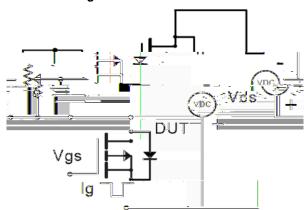


Test Circuits and Waveforms:

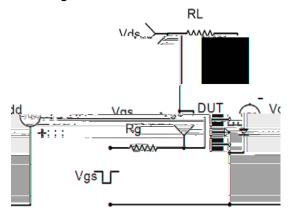
EAS Test Circuit:



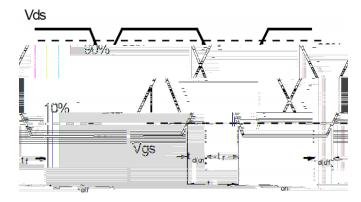
Gate Charge Test Circuit:



Switching Time Test Circuit:



Switching Waveforms:



Notes:

Calculated continuous current based on maximum allowable junction temperature.

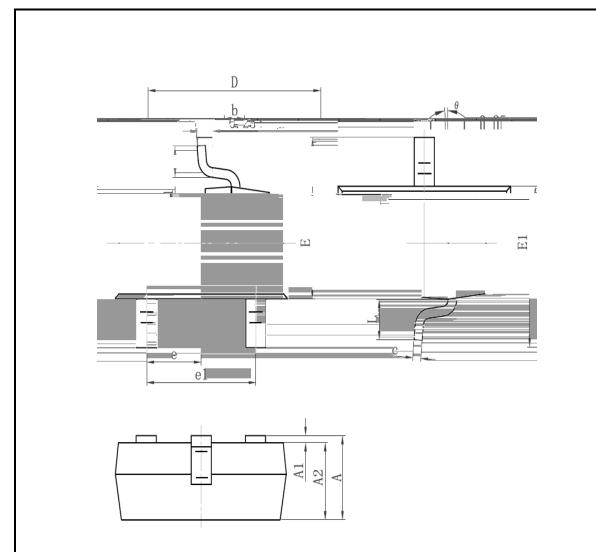
Repetitive rating; pulse width limited by max. junction temperature.

The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.

The value of R $_{A}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_{A} =25°C



Mechanical Data



Symbol	Dimension In Millimeters		Dimension In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.95TYP		0.037TYP		
e1	1.800	2.000	0.071	0.079	
L	0.55REF		0.022REF		
L1	0.300	0.500	0.012	0.020	
	00	8 ⁰	00	8 ⁰	



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